

## 1.Description

The AO3403A uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device issuitable for use as a load switch or in PWM applications.

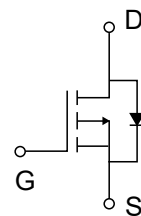
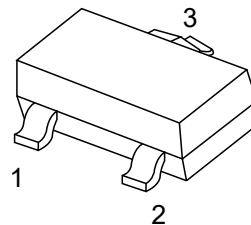
## 2.Features

- $V_{DS(V)} = -30V$
- $I_D = -2.6A (V_{GS} = -10V)$
- $R_{DS(ON)} < 103m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} < 139m\Omega (V_{GS} = -4.5V)$

## 3.Pinning information

| Pin | Symbol | Description |
|-----|--------|-------------|
| 1   | G      | GATE        |
| 2   | S      | SOURCE      |
| 3   | D      | DRAIN       |

### SOT-23



## 4.Absolute Maximum Ratings $T_A = 25^\circ C$ unless otherwise noted

| Parameter                              |                    | Symbol         | Maximum    | Units      |
|----------------------------------------|--------------------|----------------|------------|------------|
| Drain-Source Voltage                   |                    | $V_{DS}$       | -30        | V          |
| Gate-Source Voltage                    |                    | $V_{GS}$       | $\pm 12$   | V          |
| Continuous Drain Current               | $T_A = 25^\circ C$ | $I_D$          | -2.6       | A          |
|                                        | $T_A = 70^\circ C$ |                | -2.2       |            |
| Pulsed Drain Current <sup>C</sup>      |                    | $I_{DM}$       | -13        |            |
| Power Dissipation <sup>B</sup>         | $T_A = 25^\circ C$ | $P_D$          | 1.4        | W          |
|                                        | $T_A = 70^\circ C$ |                | 0.9        |            |
| Junction and Storage Temperature Range |                    | $T_J, T_{STG}$ | -55 to 150 | $^\circ C$ |

## 5.Thermal Characteristics

| Parameter                                 |              | Symbol          | Typ | Max | Units        |
|-------------------------------------------|--------------|-----------------|-----|-----|--------------|
| Maximum Junction-to-Ambient <sup>A</sup>  | $t \leq 10s$ | $R_{\theta JA}$ | 70  | 90  | $^\circ C/W$ |
| Maximum Junction-to-Ambient <sup>AD</sup> | Steady-State |                 | 100 | 125 | $^\circ C/W$ |
| Maximum Junction-to-Lead                  | Steady-State | $R_{\theta JL}$ | 63  | 80  | $^\circ C/W$ |



## 6. Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ unless otherwise noted)

| Parameter                             | Symbol             | Conditions                                                                          | Min  | Typ   | Max       | Units            |
|---------------------------------------|--------------------|-------------------------------------------------------------------------------------|------|-------|-----------|------------------|
| <b>STATIC PARAMETERS</b>              |                    |                                                                                     |      |       |           |                  |
| Drain-Source Breakdown Voltage        | $BV_{DSS}$         | $I_D=-250\mu\text{A}$ , $V_{GS}=0\text{V}$                                          | -30  |       |           | V                |
| Zero Gate Voltage Drain Current       | $I_{DSS}$          | $V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$                                           |      |       | -1        | $\mu\text{A}$    |
|                                       |                    | $T_J=55^{\circ}\text{C}$                                                            |      |       | -5        |                  |
| Gate-Body leakage current             | $I_{GSS}$          | $V_{DS}=0\text{V}$ , $V_{GS}=\pm 12\text{V}$                                        |      |       | $\pm 100$ | nA               |
| Gate Threshold Voltage                | $V_{GS(th)}$       | $V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$                                             | -0.6 | -1    | -1.4      | V                |
| On state drain current                | $I_{D(ON)}$        | $V_{GS}=-10\text{V}$ , $V_{DS}=-5\text{V}$                                          | -13  |       |           | A                |
| Static Drain-Source On-Resistance     | $R_{DS(ON)}$       | $V_{GS}=-10\text{V}$ , $I_D=-2.6\text{A}$                                           |      | 88    | 115       | $\text{m}\Omega$ |
|                                       |                    | $V_{GS}=-4.5\text{V}$ , $I_D=-2\text{A}$                                            |      | 103   | 150       | $\text{m}\Omega$ |
| Forward Transconductance              | $g_{FS}$           | $V_{DS}=-5\text{V}$ , $I_D=-2.6\text{A}$                                            |      | 8     |           | S                |
| Diode Forward Voltage                 | $V_{SD}$           | $I_S=-1\text{A}$ , $V_{GS}=0\text{V}$                                               |      | -0.78 | -1        | V                |
| Maximum Body-Diode Continuous Current | $I_S$              |                                                                                     |      |       | -1.5      | A                |
| <b>DYNAMIC PARAMETERS</b>             |                    |                                                                                     |      |       |           |                  |
| Input Capacitance                     | $C_{iss}$          | $V_{GS}=0\text{V}$ , $V_{DS}=-15\text{V}$ , $f=1\text{MHz}$                         |      | 260   | 315       | pF               |
| Output Capacitance                    | $C_{oss}$          |                                                                                     |      | 37    |           | pF               |
| Reverse Transfer Capacitance          | $C_{rss}$          |                                                                                     |      | 20    |           | pF               |
| Gate resistance                       | $R_g$              | $V_{GS}=0\text{V}$ , $V_{DS}=0\text{V}$ , $f=1\text{MHz}$                           | 4    | 8     | 12        | $\Omega$         |
| <b>SWITCHING PARAMETERS</b>           |                    |                                                                                     |      |       |           |                  |
| Total Gate Charge                     | $Q_g(10\text{V})$  | $V_{GS}=-10\text{V}$ , $V_{DS}=-15\text{V}$<br>$I_D=-2.6\text{A}$                   |      | 5.9   | 7.2       | nC               |
| Total Gate Charge                     | $Q_g(4.5\text{V})$ |                                                                                     |      | 2.8   | 3.5       | nC               |
| Gate Source Charge                    | $Q_{gs}$           |                                                                                     |      | 0.7   |           | nC               |
| Gate Drain Charge                     | $Q_{gd}$           |                                                                                     |      | 1     |           | nC               |
| Turn-On DelayTime                     | $t_{D(on)}$        | $V_{GS}=-10\text{V}$ , $V_{DS}=-15\text{V}$<br>$R_L=5.76\Omega$ , $R_{GEN}=3\Omega$ |      | 6     |           | ns               |
| Turn-On Rise Time                     | $t_r$              |                                                                                     |      | 3.5   |           | ns               |
| Turn-Off DelayTime                    | $t_{D(off)}$       |                                                                                     |      | 20    |           | ns               |
| Turn-Off Fall Time                    | $t_f$              |                                                                                     |      | 5     |           | ns               |
| Body Diode Reverse Recovery Time      | $t_{rr}$           | $I_F=-2.6\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$                                |      | 11.5  | 15        | ns               |
| Body Diode Reverse Recovery Charge    | $Q_{rr}$           | $I_F=-2.6\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$                                |      | 4.5   |           | nC               |



- A. The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- B. The power dissipation  $P_D$  is based on  $T_{J(MAX)} = 150^\circ\text{C}$ , using  $\leq 10\text{s}$  junction-to-ambient thermal resistance.
- C. Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $T_J = 25^\circ\text{C}$ .
- D. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.
- E. The static characteristics in Figures 1 to 6 are obtained using  $< 300\mu\text{s}$  pulses, duty cycle 0.5% max.
- F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, assuming a maximum junction temperature of  $T_{J(MAX)} = 150^\circ\text{C}$ . The SOA curve provides a single pulse rating.



## 7.1 Typical Electrical And Thermal Characteristics

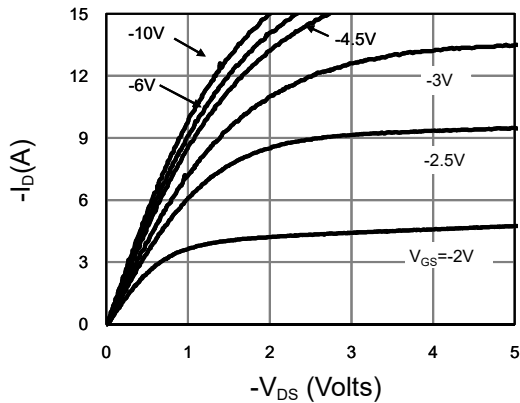


Fig 1: On-Region Characteristics (Note E)

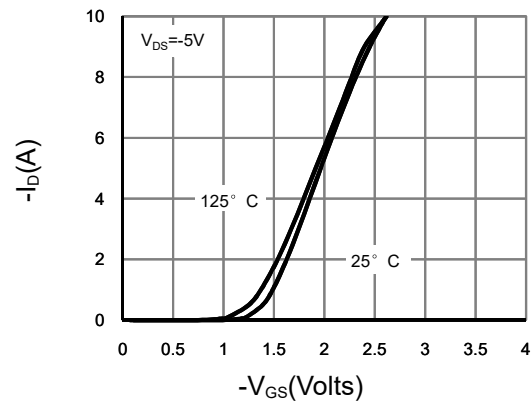


Figure 2: Transfer Characteristics (Note E)

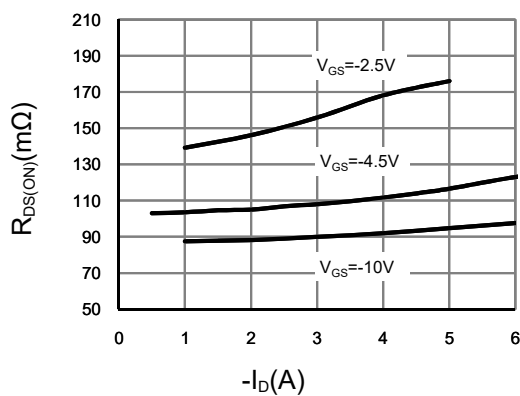


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

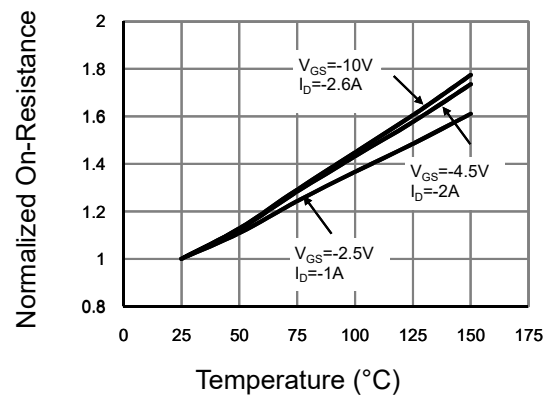


Figure 4: On-Resistance vs. Junction Temperature (Note E)

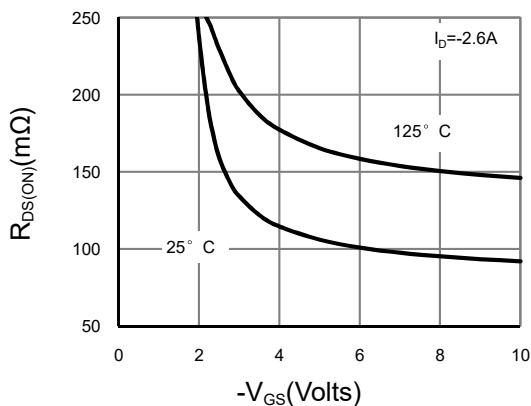


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

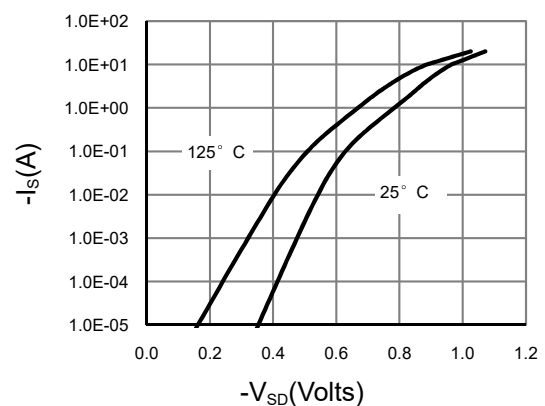


Figure 6: Body-Diode Characteristics (Note E)



## 7.2 Typical Electrical And Thermal Characteristics

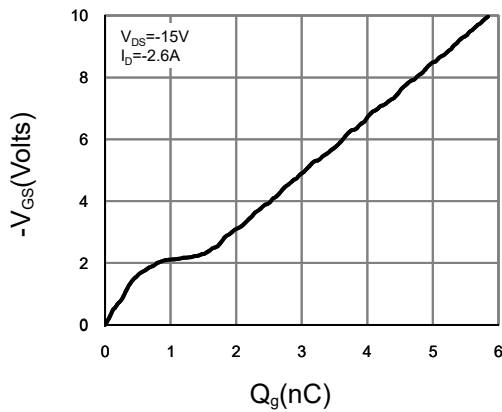


Figure 7: Gate-Charge Characteristics

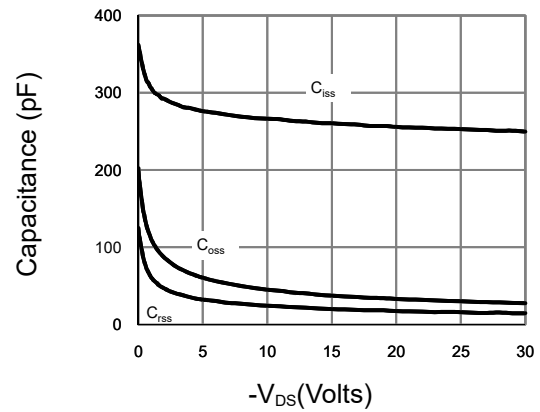


Figure 8: Capacitance Characteristics

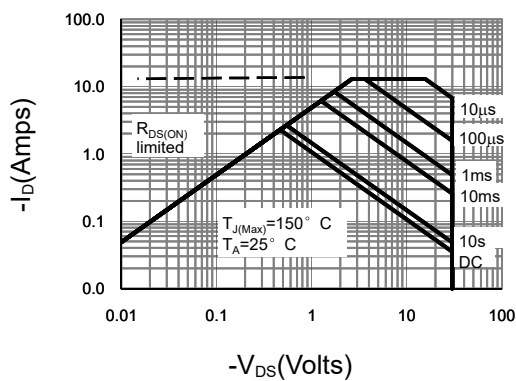


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

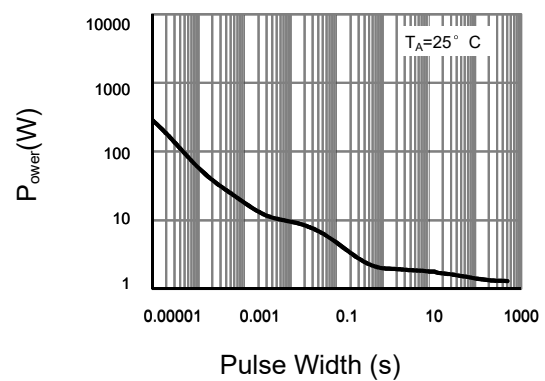


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

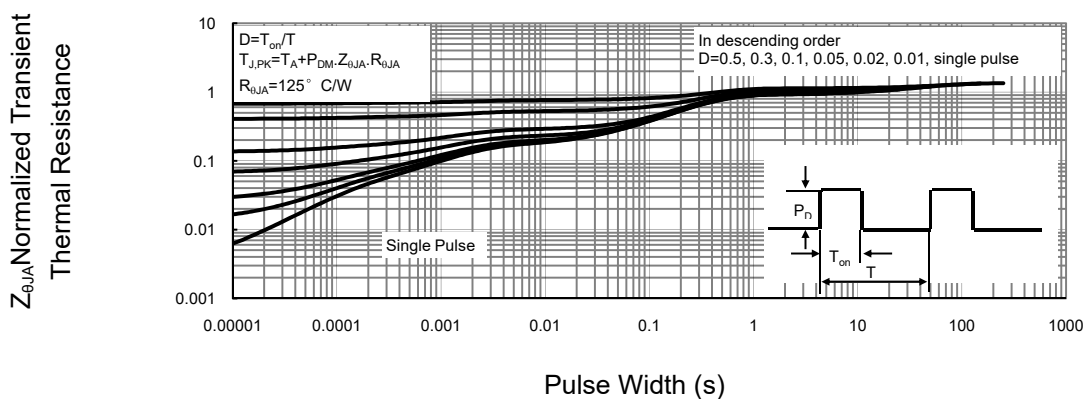
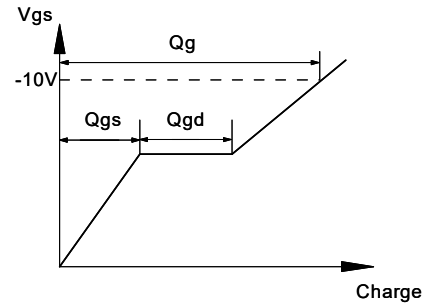
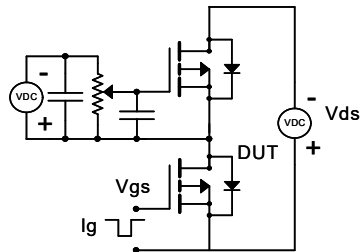


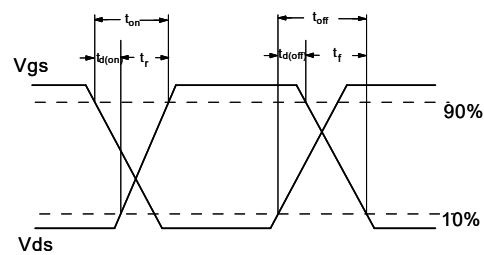
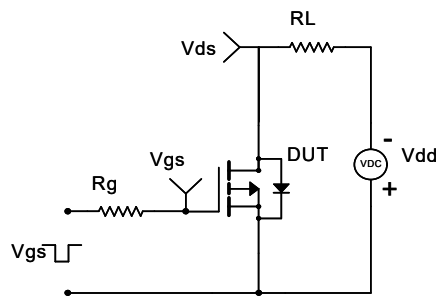
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



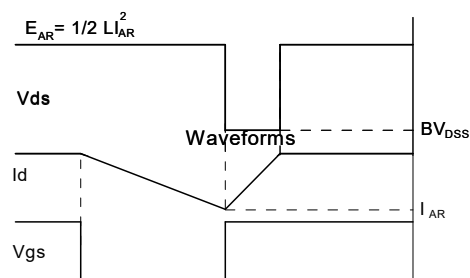
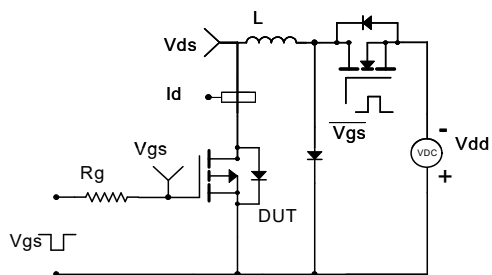
### Gate Charge Test Circuit & Waveform



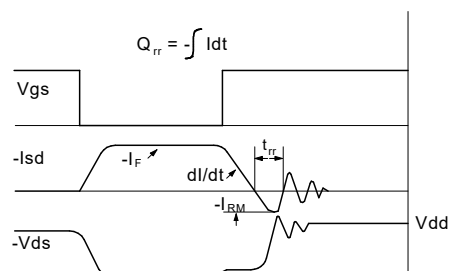
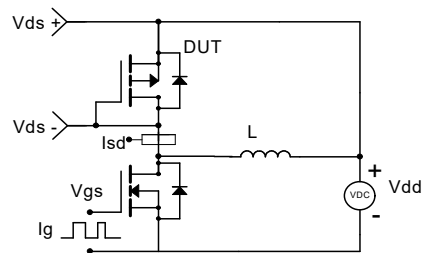
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

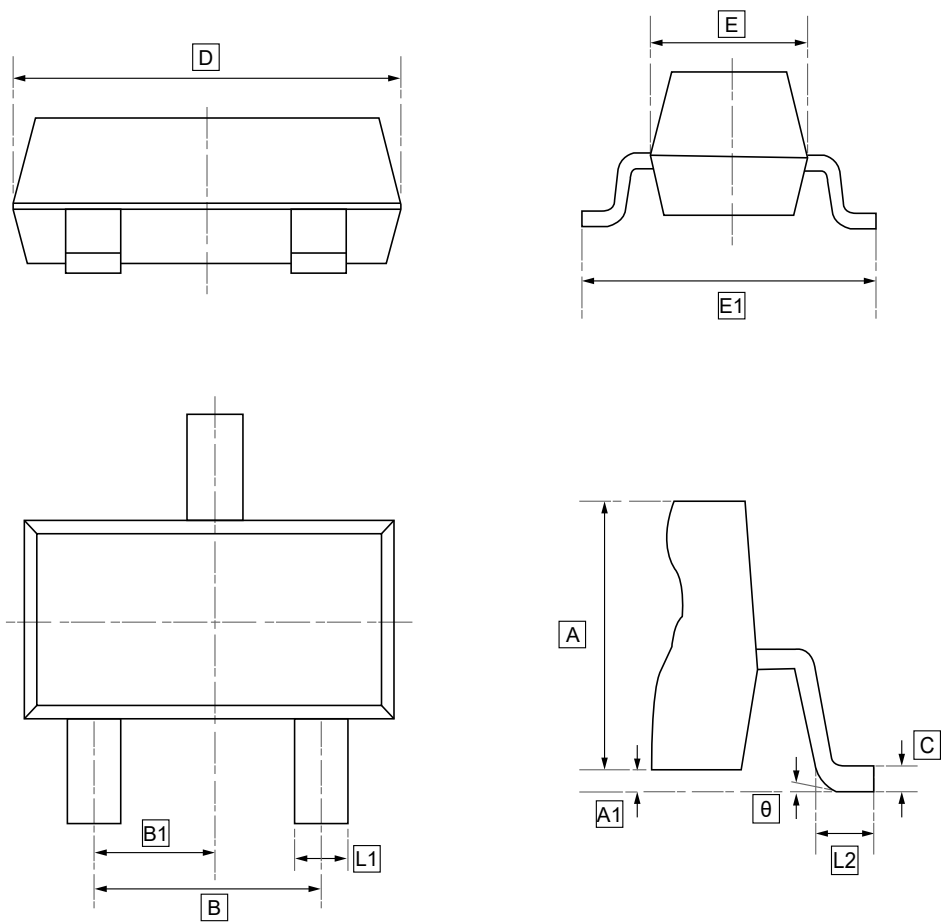


### Diode Recovery Test Circuit & Waveforms





8.SOT-23 Package Outline Dimensions

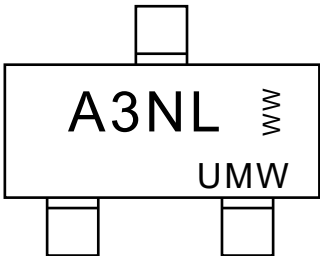


DIMENSIONS (mm are the original dimensions)

| Symbol | A     | A1    | L1    | L2    | C     | D     | E     | E1    | B     | B1    | θ  |
|--------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|----|
| Min    | 1.050 | 0.000 | 0.300 | 0.350 | 0.100 | 2.820 | 1.500 | 2.700 | 1.800 | 0.950 | 0° |
| Max    | 1.150 | 0.100 | 0.500 | 0.550 | 0.200 | 3.020 | 1.700 | 2.900 | 2.000 | TYP   | 8° |



9.Ordering information



WW: Batch Code

| Order Code  | Package | Base QTY | Delivery Mode |
|-------------|---------|----------|---------------|
| UMW AO3403A | SOT-23  | 3000     | Tape and reel |





## 10.Disclaimer

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